

**IGBT** 

# SGH15N120RUFD

# Short Circuit Rated IGBT

# **General Description**

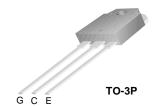
Fairchild's RUFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses as well as short circuit ruggedness. The RUFD series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

#### **Features**

- Short circuit rated 10 $\mu$ s @ T<sub>C</sub> = 100°C, V<sub>GE</sub> = 15V
- · High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.3 \text{ V}$  @  $I_{C} = 15 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD :  $t_{rr} = 70$ ns (typ.)

# **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGH15N120RUFD	Units	
V <sub>CES</sub>	Collector-Emitter Voltage		1200	V	
V <sub>GES</sub>	Gate-Emitter Voltage		± 25	V	
_	Collector Current	@ $T_C = 25^{\circ}C$	24	Α	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	15	Α	
I <sub>CM (1)</sub>	Pulsed Collector Current		45	Α	
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	15	Α	
I <sub>FM</sub>	Diode Maximum Forward Current		90	Α	
T <sub>SC</sub>	Short Circuit Withstand Time	@ T <sub>C</sub> = 100°C	10	μs	
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	180	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	72	W	
TJ	Operating Junction Temperature	-	-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second	ls	300	°C	

#### Notes:

(1) Repetitive rating : Pulse width limited by max. junction temperature

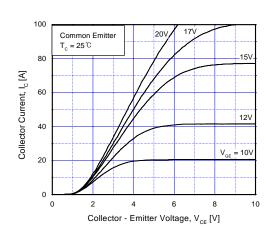
### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		0.69	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		1.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	1200			V
ΔB <sub>VCES</sub> / ΔΤ <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V			1	mA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	racteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 15$ mA, $V_{CE} = V_{GE}$	3.5	5.5	7.5	V
VGE(th)	Collector to Emitter	$I_C = 15A$ , $V_{GE} = 15V$		2.3	3.0	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 24A$ , $V_{GE} = 15V$		2.8		V
		1.C = 11.1, 1.GE 1.01	1	0		<u>-</u>
-	Characteristics					
C <sub>ies</sub>	Input Capacitance	$V_{CE} = 30V_{V_{GE}} = 0V_{V_{CE}}$		1400		pF
C <sub>oes</sub>	Output Capacitance	f = 1MHz		135		pF
C <sub>res</sub>	Reverse Transfer Capacitance	· · · · · · · · · · · · · · · · · · ·		45		pF
Switchir	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		I	20		ns
t <sub>r</sub>	Rise Time	-		60		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 15\text{A},$		60	110	ns
<u>t<sub>f</sub></u>	Fall Time	$R_G = 20\Omega$ , $V_{GE} = 15V$ ,		150	300	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		1.0		mJ
E <sub>off</sub>	Turn-Off Switching Loss	-		0.98		mJ
E <sub>ts</sub>	Total Switching Loss			1.98	2.8	mJ
t <sub>d(on)</sub>	Turn-On Delay Time			20		ns
t <sub>r</sub>	Rise Time	-		70		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 15\text{A},$		80	150	ns
t <sub>f</sub>	Fall Time	$R_G = 20\Omega$ , $V_{GE} = 15V$ ,		200	400	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C		1.13		mJ
E <sub>off</sub>	Turn-Off Switching Loss	1		1.50		mJ
E <sub>ts</sub>	Total Switching Loss	-		2.63	3.81	mJ
T <sub>sc</sub>	Short Circuit Withstand Time	V <sub>CC</sub> = 600 V, V <sub>GE</sub> = 15V @ T <sub>C</sub> = 100°C	10			μs
Qg	Total Gate Charge			72	108	nC
_ <del>y</del>	Gate-Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 15\text{A},$		10	15	nC
Q <sub>aa</sub>			1	11	1 -	_
Q <sub>ge</sub> Q <sub>gc</sub>	Gate-Collector Charge	V <sub>GE</sub> = 15V		30	45	nC

# Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condit	Min.	Тур.	Max.	Units	
	Diode Forward Voltage	I <sub>F</sub> = 15A	$T_C = 25^{\circ}C$		2.9	3.5	V
$V_{FM}$			T <sub>C</sub> = 100°C		2.7		
	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		70	100	ns
<sup>L</sup> rr		I <sub>F</sub> = 15A dI/dt = 200 A/μs	T <sub>C</sub> = 100°C		85		
	Diode Peak Reverse Recovery		$T_C = 25^{\circ}C$		7.0	9.0	Α
ı <sub>tt</sub>	Current		T <sub>C</sub> = 100°C		8.5		A
Q <sub>rr</sub>	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		245	450	nC
			T <sub>C</sub> = 100°C		360		110



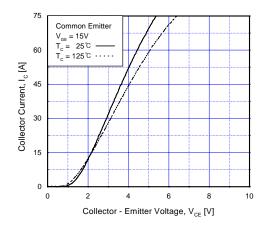
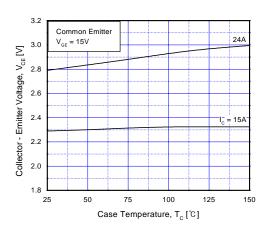


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



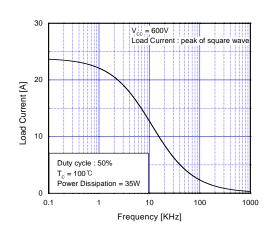
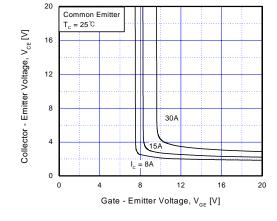


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



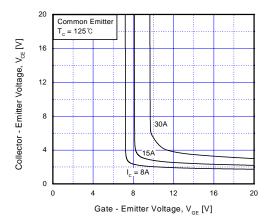
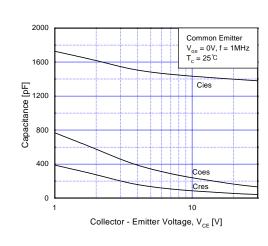


Fig 5. Saturation Voltage vs. V<sub>GE</sub>

Fig 6. Saturation Voltage vs.  $V_{\text{GE}}$ 

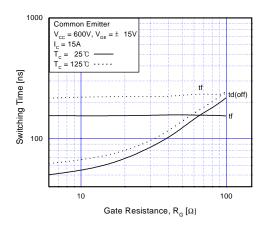
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Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



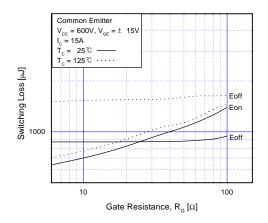
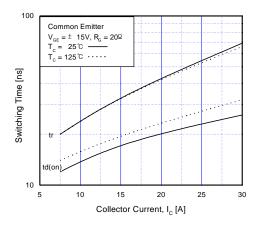


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



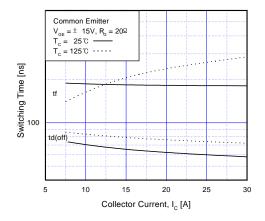
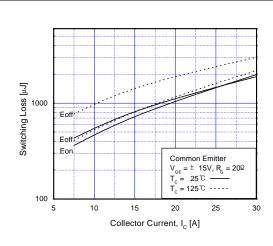


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



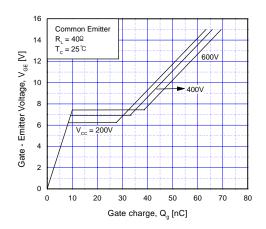
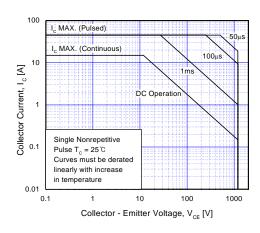


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



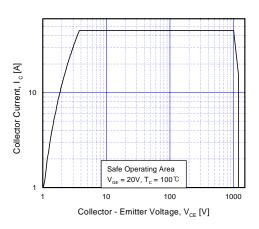


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

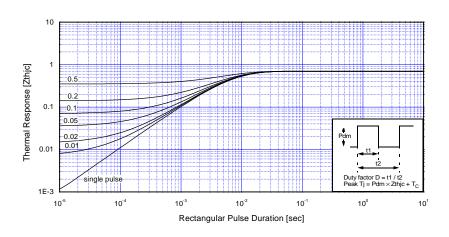
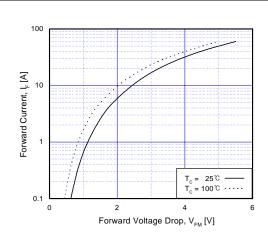


Fig 17. Transient Thermal Impedance of IGBT



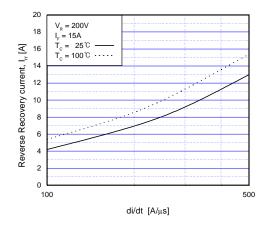
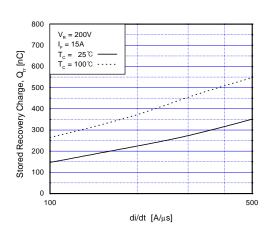


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



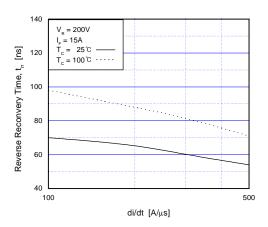
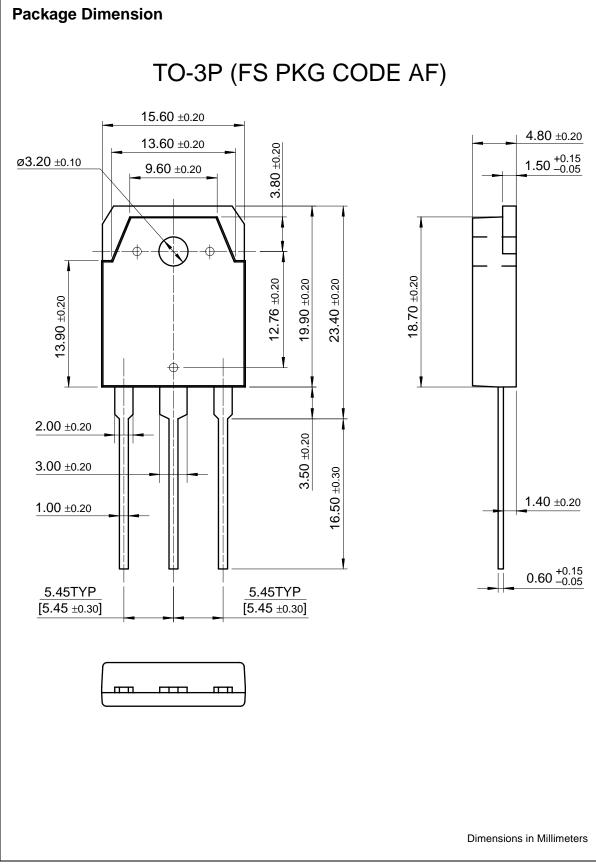


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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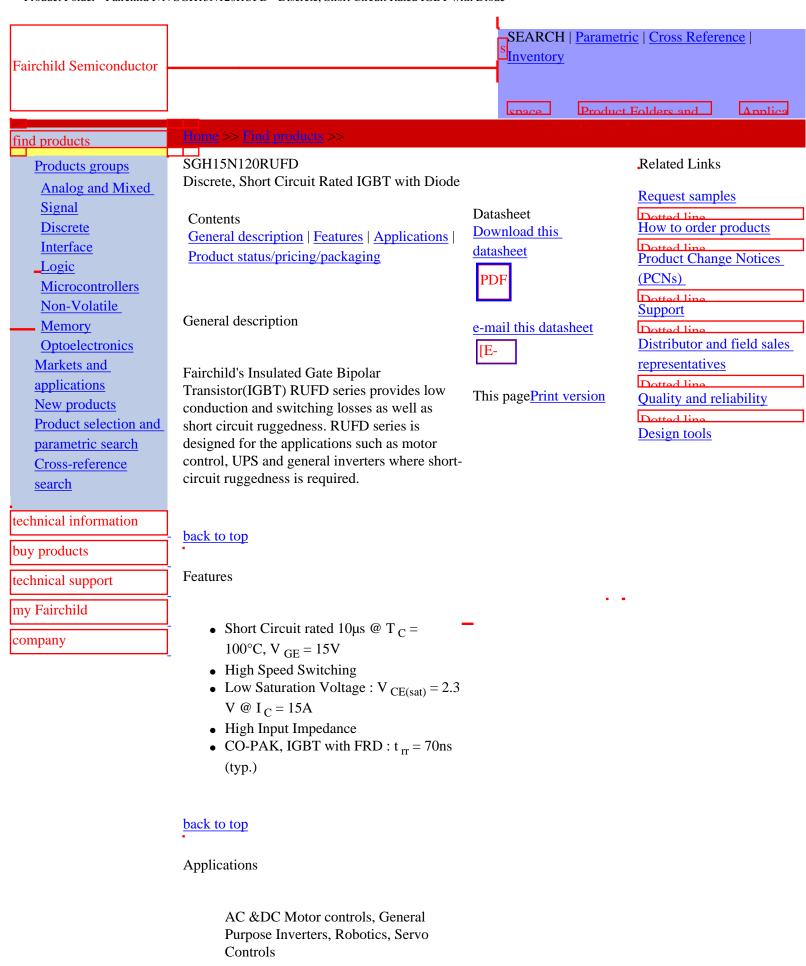
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Product	Product status	Pricing*	Inventory check & ordering	Package type	Leads	Packing method
SGH15N120RUFDTU	Full Production	\$6.73	Purchase	TO-3P	3	RAIL

<sup>\*</sup> Fairchild 1,000 piece Budgetary Pricing

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